USB3.1C S1V DN1 RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

General ordering data

Version	OMNIMATE Data - USB jack, PCB plug-in connector, USB jacks, Type C, SMD solder connection, 180°, Plugging cycles: ≥ 10000, Pitch in mm (P): 0.50, Number of poles: 24, LCP, Reel
Order No.	2987540000
Type	USB3.1C S1V DN1 RL
GTIN (EAN)	4099986854994
Qty.	450 pc(s).
Packaging	Reel

Creation date October 5, 2024 2:48:55 AM CEST

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Technical data

Dimensions and weights

Depth	4.3 mm	Depth (inches)	0.169 inch
Height	9.25 mm	Height (inches)	0.364 inch
Width	8.94 mm	Width (inches)	0.352 inch
Net weight	10 g		

System specifications

Mounting onto the PCB	SMD solder connection	Number of poles	24
Number of solder pins per pole	1	Outgoing elbow	180°
Pitch in mm (P)	0.5 mm	Plugging cycles	≥ 10000
Product family	OMNIMATE Data - USB jack	Protection degree	IP20
Shield surface	nickel-plated	Shield tabs	none
Shielding	360° shield contact	Shielding material	Stainless steel, Brass
Side termination, characteristic	None	Solder pin length (l)	1.15 mm
Soldering process	Reflow soldering, Manual soldering		

Electrical properties

Dielectric strength, contact / contact	750 V AC	Insulation strength	≥ 100 MΩ
Rated voltage	5 V		

Material data

Insulating material	LCP	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 100 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact base material	Copper alloy	Contact material	Phosphor bronze alloy
Contact surface	Gold over nickel	Operating temperature, min.	-30 °C
Operating temperature, max.	80 °C		

Packing

Packaging	Reel	VPE length	0
VPE width	0	VPE height	0

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01
ECLASS 13.0	27-46-02-01	ECLASS 14.0	27-46-02-01

Environmental Product Compliance

REACH SVHC	/
RoHS Compliance Status	Compliant

Approvals

ROHS	Conform

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Technical data

Downloads

Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format

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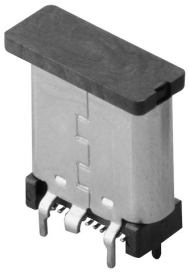
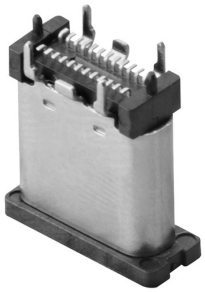
Drawings





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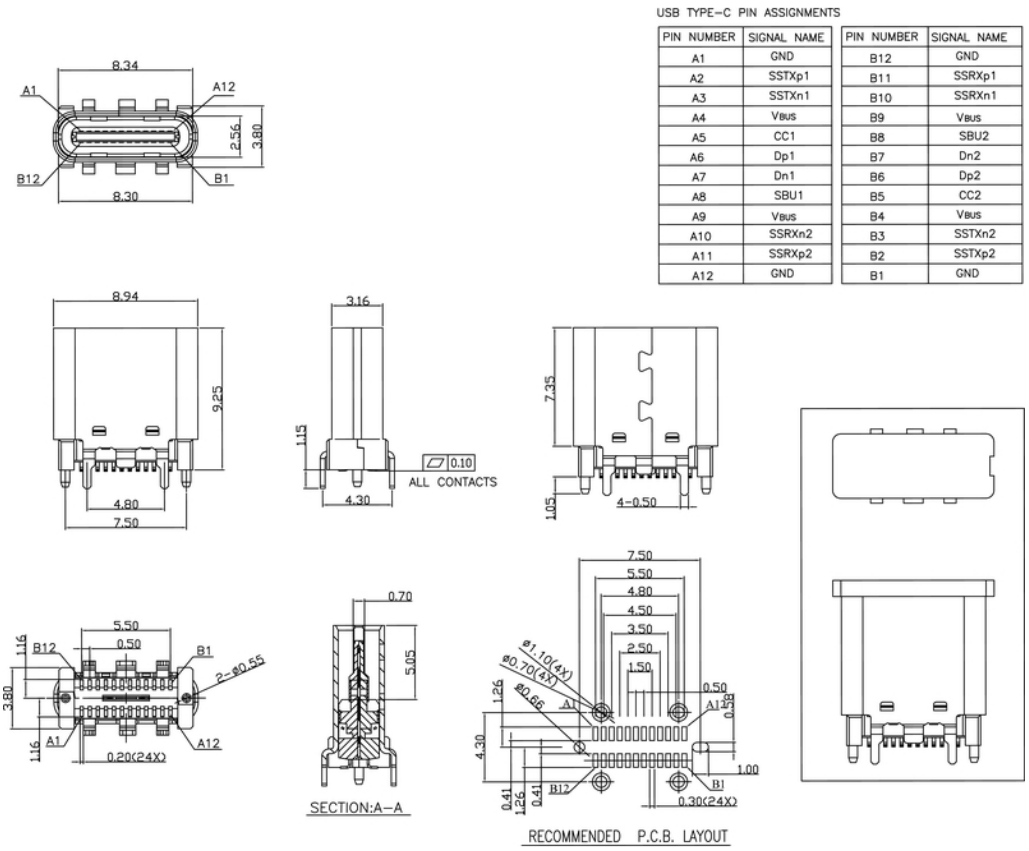

Reflow Solder Profile

Recommended reflow soldering profile

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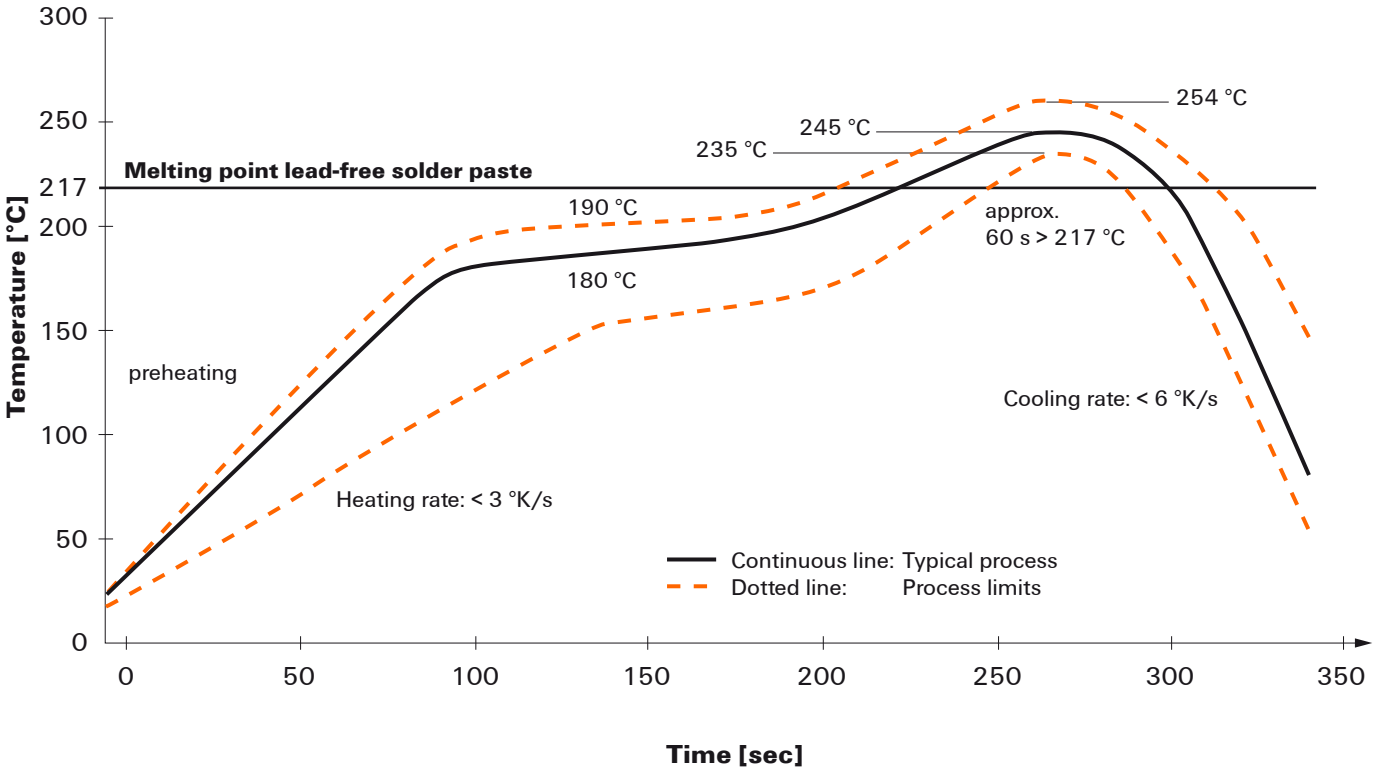

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.